HIGH DENSITY INTERNAL BALL GRID ARRAY INTEGRATED CIRCUIT PACKAGE

ABSTRACT OF THE DISCLOSURE

An integrated circuit package (30) comprising a substrate (70) having peripheral openings (86) and first and second surfaces (92, 94), a plurality of routing strips (82) being integral with the substrate (70), a plurality of pads (100) centrally disposed on the first surface (92) and electrically connected with at least one of the routing strips (82), a chip (50) having bonding pads (120) adhered to the second surface (84) of the substrate (70), wire bonding (80) electrically connecting at least one bonding pad (120) to at least one of the routing strips (82) and potting material (90) filling the openings (86) to adhere the chip (50) to the substrate (70) and surrounding the wire bonding (80), is disclosed.

Figure 2